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|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------|---------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------------------|---------------------|
| PCN Number: | 20210406000.1 | | PCN Date: | Apr 6 2021 | |
| Title: | Qualification of CDAT as an alternate Assembly site for Select Devices | | | | |
| Customer Contact: | PCN Manager | Dept: | Quality Services | | |
| Proposed 1st Ship Date: | Jul 5 2021 | Estimated Sample Availability: | Date provided at sample request | | |
| Change Type: | | | | | |
| <input checked="" type="checkbox"/> | Assembly Site | <input type="checkbox"/> | Design | <input type="checkbox"/> | Wafer Bump Site |
| <input type="checkbox"/> | Assembly Process | <input type="checkbox"/> | Data Sheet | <input type="checkbox"/> | Wafer Bump Material |
| <input type="checkbox"/> | Assembly Materials | <input type="checkbox"/> | Part number change | <input type="checkbox"/> | Wafer Bump Process |
| <input type="checkbox"/> | Mechanical Specification | <input type="checkbox"/> | Test Site | <input type="checkbox"/> | Wafer Fab Site |
| <input type="checkbox"/> | Packing/Shipping/Labeling | <input type="checkbox"/> | Test Process | <input type="checkbox"/> | Wafer Fab Materials |
| | | | | <input type="checkbox"/> | Wafer Fab Process |
| PCN Details | | | | | |
| Description of Change: | | | | | |
| Texas Instruments Incorporated is announcing the qualification of CDAT as an additional Assembly site for the list of devices shown below. There are no construction differences between the 2 sites. | | | | | |
| Reason for Change: | | | | | |
| Supply continuity | | | | | |
| Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative): | | | | | |
| None | | | | | |
| Anticipated impact on Material Declaration | | | | | |
| <input checked="" type="checkbox"/> | No Impact to the Material Declaration | <input type="checkbox"/> | Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp | | |
| Changes to product identification resulting from this PCN: | | | | | |
| Assembly Site | Assembly Site Origin (22L) | Assembly Country Code (23L) | Assembly City | | |
| CLARK | QAB | PHL | Angeles City, Pampanga | | |
| CDAT | CDA | CHN | Chengdu | | |
| Sample product shipping label (not actual product label) | | | | | |
| | | | | | |
| Product Affected: | | | | | |
| SN62085RLTR | TLV62085RLTT | TPS62085RLTR | TPS62085RLTT | | |
| TLV62085RLTR | | | | | |

Change Qualification Report

Approve Date 15-Mar-2021

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

| Type | Test Name / Condition | Duration | Qual Device: TPS62085RLTR | QBS Package Reference: TPS51393RJE |
|-------|-------------------------------------|-------------------------|------------------------------|---------------------------------------|
| BHAST | Biased Humidity 130C | 96 hours | QBS | 3/231/0 |
| HTSL | High Temp Storage Bake 170C | 420 Hours | QBS | 3/231/0 |
| MQ | Manufacturability (Assembly) | (per TI specifications) | Pass | Pass |
| MQ | Manufacturability (Bump) | (per TI specifications) | Pass | Pass |
| SD | Pb Free Surface Mount Solderability | Pb Free/Solder | QBS | 3/66/0 |
| TC | Temperature Cycle, -55/125C | 700 Cycles | QBS | 3/231/0 |
| | Temperature Cycle, -65/150C | 500 cycles | 1/77/0 | - |
| UHAST | Unbiased HAST 130C/85%RH | 96 Hours | QBS | 3/231/0 |

- QBS: Qual By Similarity

- Qual Device TPS62085RLTR is qualified at LEVEL1-260CG

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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